

# PRESS RELEASE

-----  
PRESS RELEASE

08.05.2024 || Page 1 | 2  
-----

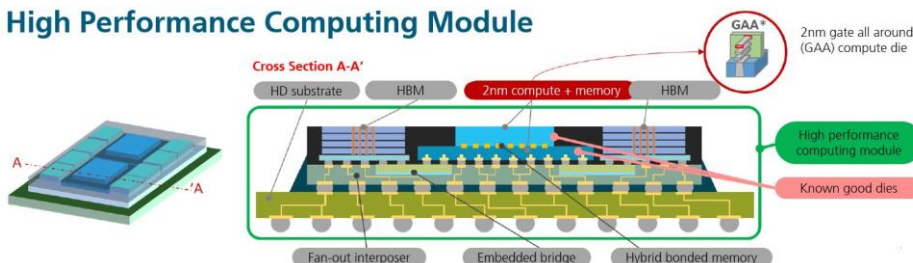
## Rapidus and Fraunhofer IZM join Forces for High-End Performance Packaging

**Rapidus Corporation, Japan's high-end microelectronics manufacturer founded in 2022, and Fraunhofer IZM, a world-leading research institute for advanced microelectronic packaging, join forces for advanced packaging solutions for 2nm node high performance computing modules.**

Rapidus is building a fab on the island of Hokkaido to manufacture 2nm node microchips and the related high-end performance package. METI, Japan's ministry of economy, trade and industry, approves Rapidus' plan for research and development of 2nm generation semiconductor integration technology for 2024. Thus, Fraunhofer IZM is happy to announce this corporation for one of the most important topics in the near future, realizing modules for e.g. 5G communications, autonomous driving or high performance computing.

Dr. Michael Schiffer, project leader at Fraunhofer IZM, says: „In March, we had a very inspiring meeting with Rapidus' president, Dr. Atsuyoshi Koike, in which he clearly emphasized the importance, not only to develop the most advanced node chip technology but also a highly advanced packaging technology to enable overall best-in-class performance. I'm really looking forward to a fruitful cooperation with full commitment by everyone involved!“

### High Performance Computing Module



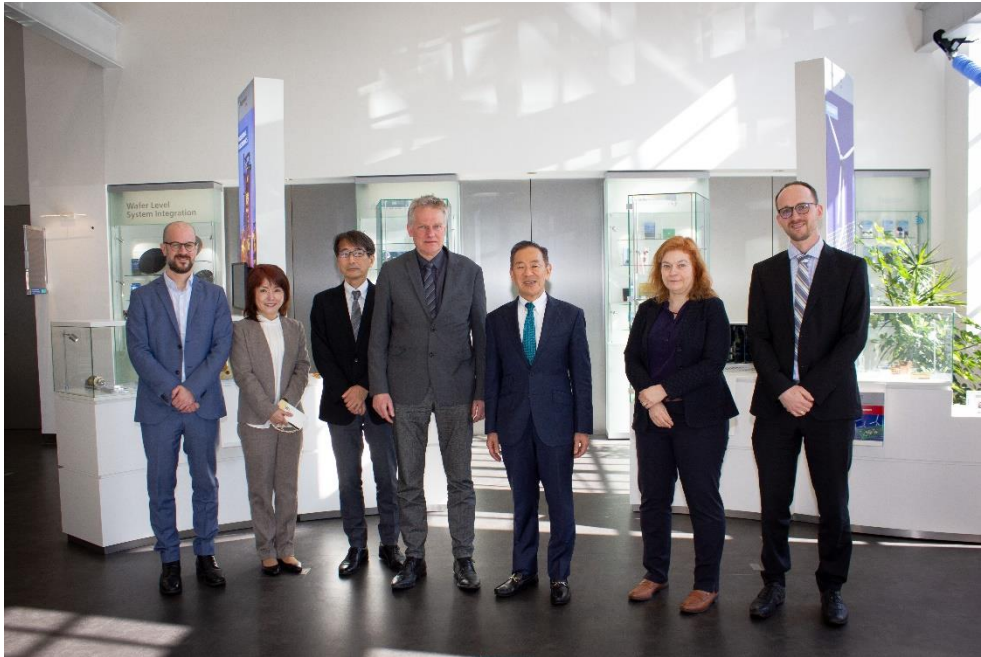
**High Performance Computing Module. © Rapidus: Adopted and translated from: [https://www.meti.go.jp/policy/mono\\_info\\_service/joho/post5g/pdf/240402\\_theme\\_01.pdf](https://www.meti.go.jp/policy/mono_info_service/joho/post5g/pdf/240402_theme_01.pdf) | Graphic in print quality: [www.izm.fraunhofer.de/en/news\\_events/pics.html](http://www.izm.fraunhofer.de/en/news_events/pics.html)**

---

#### Editorial office

Georg Weigelt | Phone +49 30 46403-279 | [georg.weigelt@izm.fraunhofer.de](mailto:georg.weigelt@izm.fraunhofer.de) |

Fraunhofer Institute for Reliability and Microintegration IZM | Gustav-Meyer-Allee 25 | 13355 Berlin | [www.izm.fraunhofer.de](http://www.izm.fraunhofer.de) |

**FRAUNHOFER INSTITUTE FOR RELIABILITY AND MICROINTEGRATION IZM**

---

**PRESS RELEASE**08.05.2024 || Page 2 | 2

---

**Dr. A Koike (President of Rapidus Corp., 3rd fr. right) and Prof. Dr. M. Schneider-Ramelow (Director of Fraunhofer IZM, 4th fr. right) © Fraunhofer IZM | Picture in print quality: [www.izm.fraunhofer.de/en/news\\_events/pics.html](http://www.izm.fraunhofer.de/en/news_events/pics.html)**

---

The **Fraunhofer-Gesellschaft**, based in Germany, is the world's leading organization for application-oriented research. With its focus on future-relevant key technologies as well as on the exploitation of results in business and industry, it plays a central role in the innovation process. As a guide and source of inspiration for innovative developments and scientific excellence, it helps to shape our society and our future. Founded in 1949, the organization currently operates 76 institutes and research facilities in Germany. Around 30,000 employees, most of them with scientific or engineering training, work on the annual research volume of 3,0 billion euros. Of this, 2.6 billion euros are attributable to contract research.

Highly integrated microelectronics are omnipresent and yet often evade the eye. With 4 central technology clusters, **Fraunhofer IZM** covers a wide range of areas in quantum, as well as medical, communications and high-frequency technology. With our world-leading expertise, we offer our customers cost-effective development and reliability assessment of electronic packaging technologies, as well as custom-tailored system integration technologies at wafer, chip and board level. For over 30 years and at 3 locations, we have been supporting start-ups as well as medium-sized and large international companies (with knowledge transfer) and researching key technologies for intelligent electronic systems of the future.

---

**Specialist contact person**Dr. Michael Schiffer | Phone +49 30 46403-234 | [michael.schiffer@izm.fraunhofer.de](mailto:michael.schiffer@izm.fraunhofer.de) |Fraunhofer Institute for Reliability and Microintegration IZM | Gustav-Meyer-Allee 25 | 13355 Berlin | [www.izm.fraunhofer.de](http://www.izm.fraunhofer.de) |